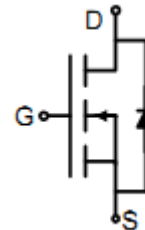




**Features**

For a single MOSFET

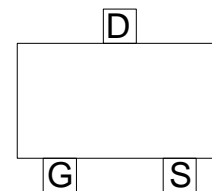
- $V_{DS} = 20V$
- $R_{DS(ON)} = 21m\Omega @ V_{GS}=4.5V$
- $R_{DS(ON)} = 30m\Omega @ V_{GS}=2.5V$



**General Description**

Advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and low operation voltage. This device is suitable for using as a load switch or in PWM applications.

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device



**Pin configurations**

See Diagram below

Absolute Maximum Ratings					
Parameter		Symbol	Rating	Units	
Drain-Source Voltage		$V_{DS}$	20	V	
Gate-Source Voltage		$V_{GS}$	$\pm 10$	V	
Drain Current	Continuous	$I_D$	6	A	
	Pulsed <sup>1</sup>		25		
Total Power Dissipation	@TA=25°C	$P_D$	1.5	W	
Operating Junction Temperature Range		$T_J$	-55 to 175	°C	
Thermal Resistance					
Symbol	Parameter		Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		-	83.5	°C/W

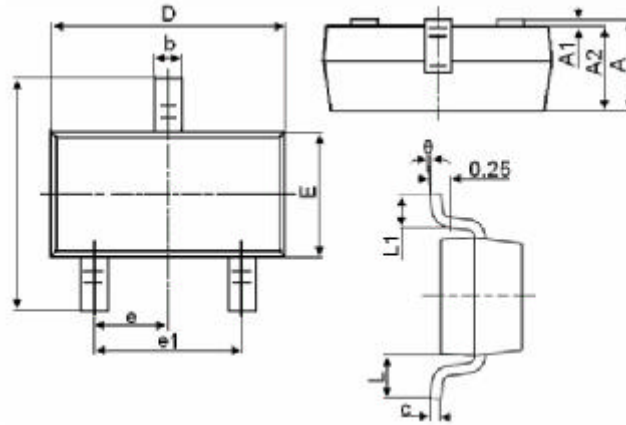


Electrical Characteristics (T <sub>J</sub> =25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS (Note 2)</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0 V	20			V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> =0V			0.8	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =10V			80	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	0.45	0.65	1.2	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.5A	-	21	24.8	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =3.5A		30	34.8	mΩ
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =8V, f=1MHz		600		pF
C <sub>oss</sub>	Output Capacitance			330		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			140		pF
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V, I <sub>D</sub> =1A		10	15	nC
Q <sub>gs</sub>	Gate Source Charge			2.3		nC
Q <sub>gd</sub>	Gate Drain Charge			3		nC
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V, R <sub>GEN</sub> =6Ω I <sub>D</sub> =1A		10	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			11	25	ns
t <sub>d(r)</sub>	Turn-On Rise Time			35	70	ns
t <sub>d(f)</sub>	Turn-Off Fall Time			30	60	ns



Package Outline Dimension

SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	θ°

Notes

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified.
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.